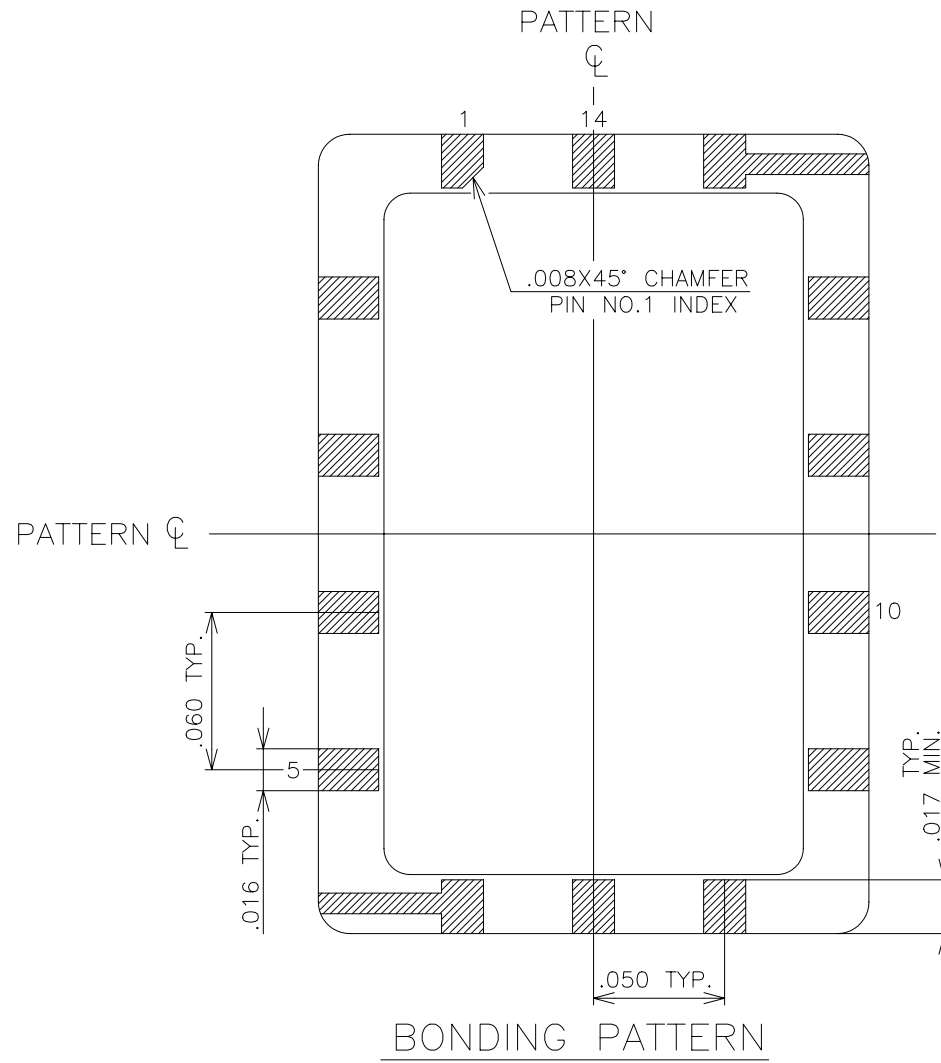


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

DETAIL A

MODIFICATION							NAME 14 LEAD FLAT PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN S.T	CHECKED T.A	APPROVED M.F	DATE DEC.28.89	FBO14W980-1 S=0 D=0
	REDRAWN : CONVERTED CAD DATA. ADDED : SHEET 2/2	JUL.31.00	H.K	H.TA/S.NI	H.SA	SCALE 8 / 1	MATERIAL AS INDICATED						DRAWING NO. KD-F89980-D
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA	KYOCERA CORPORATION KYOTO JAPAN					



MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	H.K	H.TA/S.NI	H.SA	JUL.31.'00
						SCALE 20 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
△	ADDED : THIS SHEET	JUL.31.'00	H.K	H.TA/S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-F89980-D	SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			2 / 2			